



International Electronics Manufacturing Initiative

iNEMI Optoelectronic TIG Potential New Projects Review & Discussion

Champions:

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Anaheim Marriott - March 6, 2005

The iNEMI Optoelectronic (OE) TIG reviewed a number of proposed projects in March 2005 at their TIG's Gap review meeting - OFC/NFOEC 2005

Future Proposed Projects:

- Develop a practical comparison metric - accuracy of the internal loss estimators used in optic fusion splices
- Investigate contamination and defects for parallel connectors, such as the MT-P and high I/O array connectors

- Apply iNEMI member resources to identifying and lowering the barrier(s) to widespread adoption of optical interconnects "within the box", for IT and telecom applications
- "Near hermetic" Optoelectronic packages. Evaluate lower cost packaging materials and sealing methods for datacom applications
- Evaluate innovative approaches in Optoelectronic packaging - with assembly or test
- Review Bio-medical, automotive, aerospace, security, or similar (non-communications) applications

Open Discussion